

SAW components

SAW Rx filter

Automotive telematics
TD-LTE band 40

Series/type:	B4352
Ordering code:	B39242B4352P810

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SAW Rx filter	2350 MHz

Data sheet

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1 Application

- Low-loss RF filter for TD-LTE Band 40 system, receive path (Rx)
- Suitable for diversity applications
- Usable pass band 100 MHz

2 Features

- Package size $1.4 \pm 0.1 \text{ mm} \times 1.1 \pm 0.1 \text{ mm}$
- Package height 0.45 mm (max.)
- Package code QCS5P
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- AEC-Q200 qualified component family (operable temperature range $-40 \text{ }^{\circ}\text{C}$ to $+85 \text{ }^{\circ}\text{C}$)
- Electrostatic Sensitive Device (ESD)

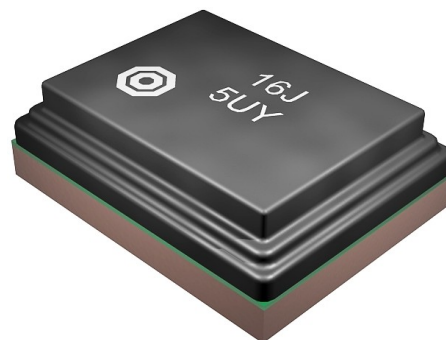
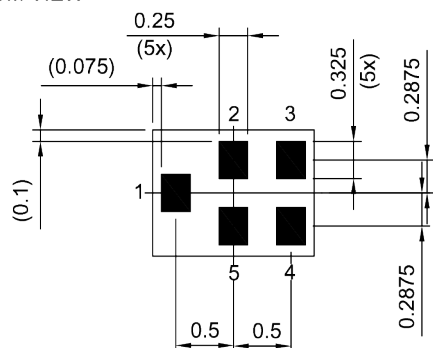


Figure 1: Picture of component with example of product marking.

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3 Package

BOTTOM VIEW

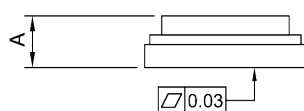


Pad and pitch tolerance ±0.05

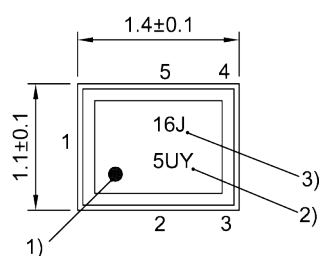
4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

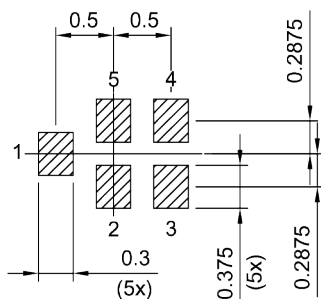
SIDE VIEW



TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern
THRU VIEW


Landing pad tolerance -0.02

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 16).

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5 Matching circuit

$$\blacksquare L_{p1} = 4.7 \text{ nH}$$

$$\blacksquare L_{p4} = 6.2 \text{ nH}$$

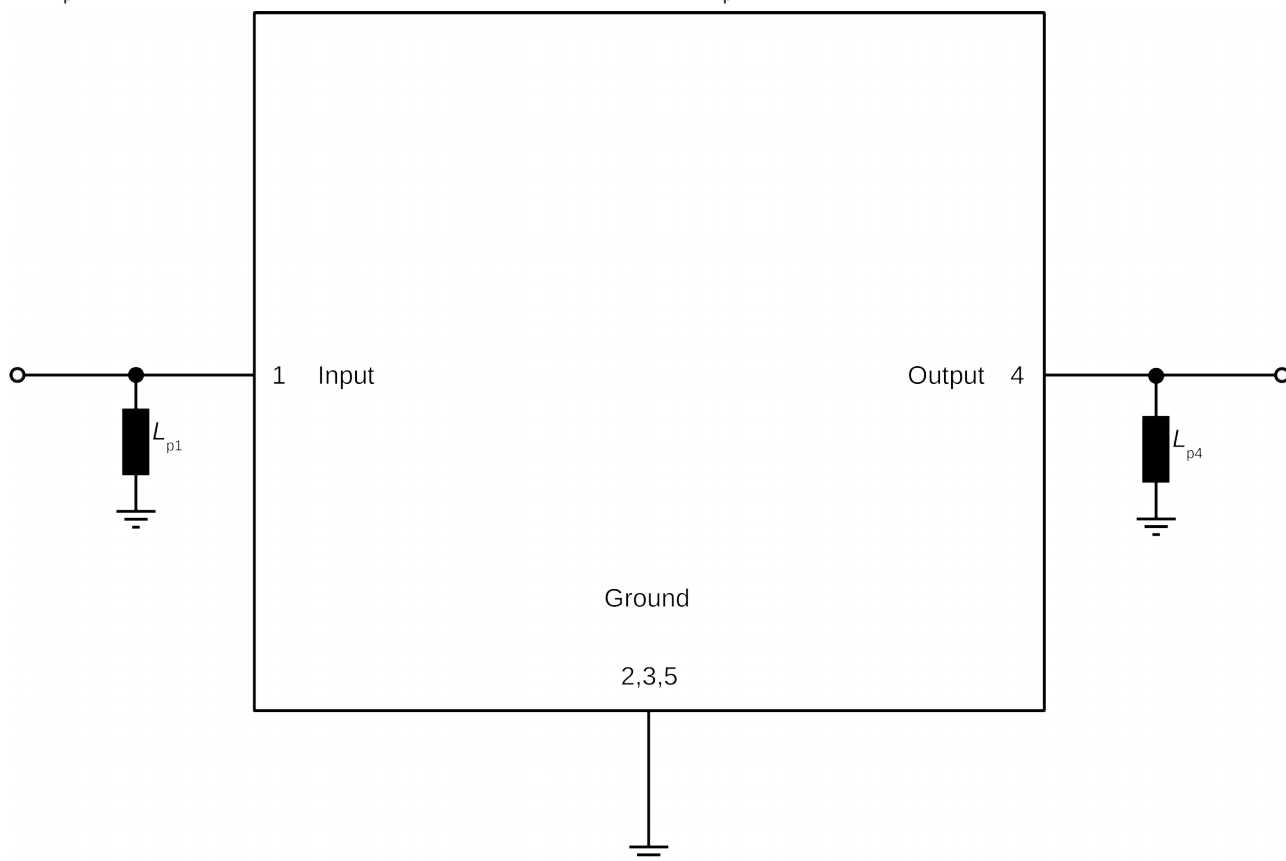


Figure 3: Schematic of matching circuit.

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6 Characteristics

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
Input terminating impedance	Z_{IN}	= 50 Ω with par. 4.7 nH ¹⁾
Output terminating impedance	Z_{OUT}	= 50 Ω with par. 6.2 nH ¹⁾

Characteristics			min. for T_{SPEC}	typ. @+25 °C	max. for T_{SPEC}	
Center frequency		f_C	—	2350	—	MHz
Maximum insertion attenuation		α_{max}	—	2.8	4.0	dB
	2300... 2400	MHz	—	2.8	4.0	
Amplitude ripple (p-p)		$\Delta\alpha$	—	1.4	2.8	dB
	2300... 2400	MHz	—	1.4	2.8	
Maximum VSWR		$VSWR_{max}$	—	1.8	2.3	
@ input port	2300... 2400	MHz	—	1.8	2.3	
@ output port	2300... 2400	MHz	—	1.9	2.3	
Minimum attenuation		α_{min}				
	50... 1559	MHz	40	54	—	dB
	1559... 1606	MHz	40	57	—	dB
	1606... 2125	MHz	36	40	—	dB
	2125... 2215	MHz	30	38	—	dB
	2215... 2240	MHz	30	36	—	dB
	2430... 2440	MHz	12	35	—	dB
	2440... 2450	MHz	31	36	—	dB
	2450... 2500	MHz	32	41	—	dB
	2500... 2690	MHz	33	37	—	dB
	4600... 4800	MHz	26	35	—	dB
	4900... 5950	MHz	24	33	—	dB

¹⁾ See Sec. Matching circuit (p. 5).

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7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +85\text{ °C}$	
Storage temperature	$T_{STG} = -40\text{ °C} \dots +85\text{ °C}$	
DC voltage	$V_{DC} = 0\text{ V}$	
Input power @ input port: 2300 ... 2400 MHz	$P_{IN} = 16\text{ dBm}$	Continuous wave for 2000 h @ 55 °C.

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8 Transmission coefficient

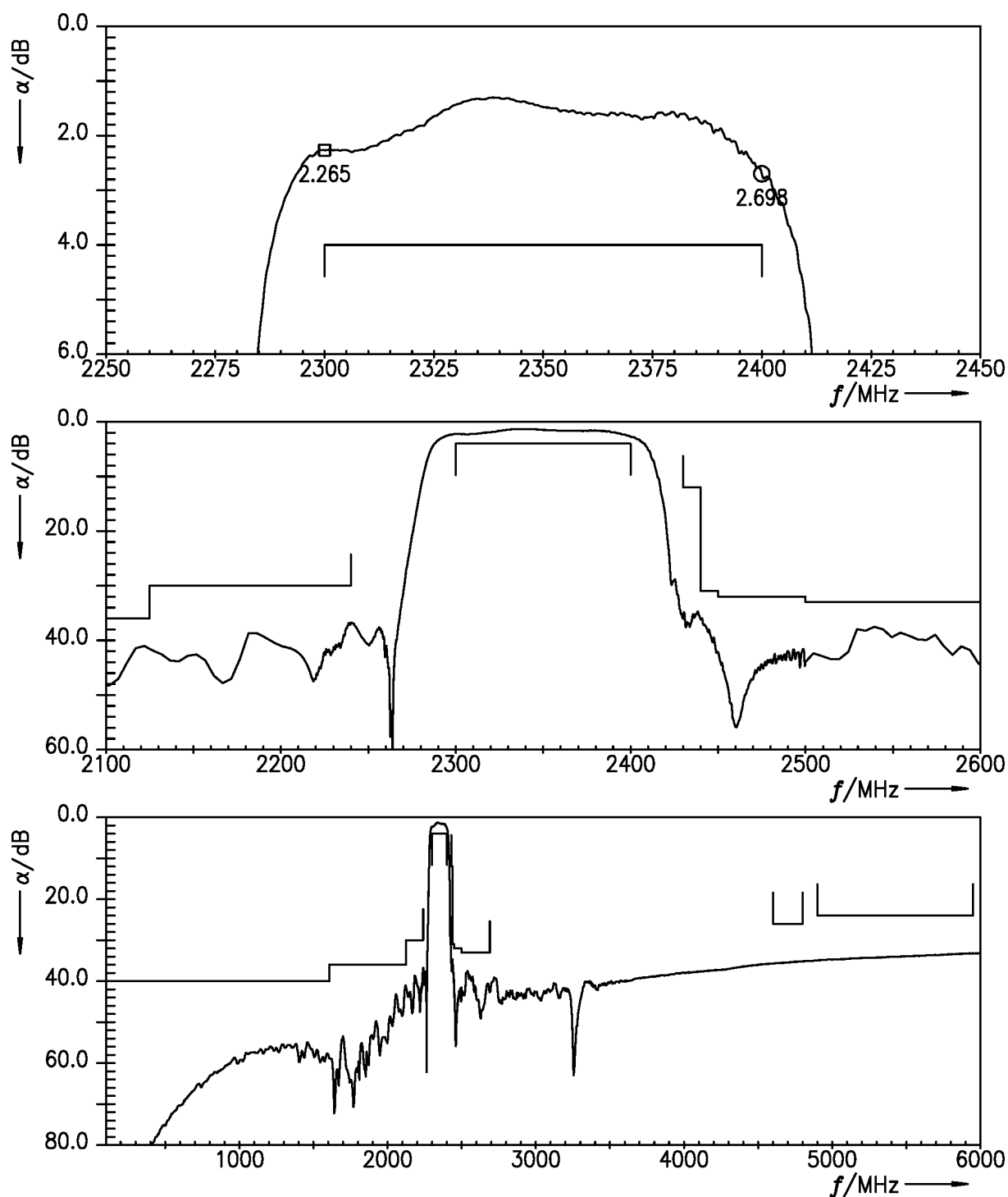


Figure 4: Attenuation.

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9 Reflection coefficients

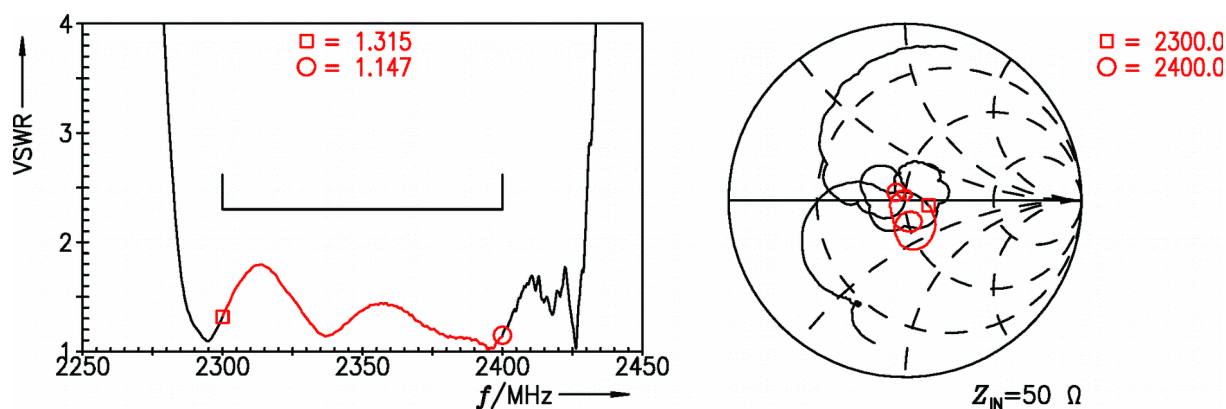


Figure 5: Reflection coefficient at IN port.

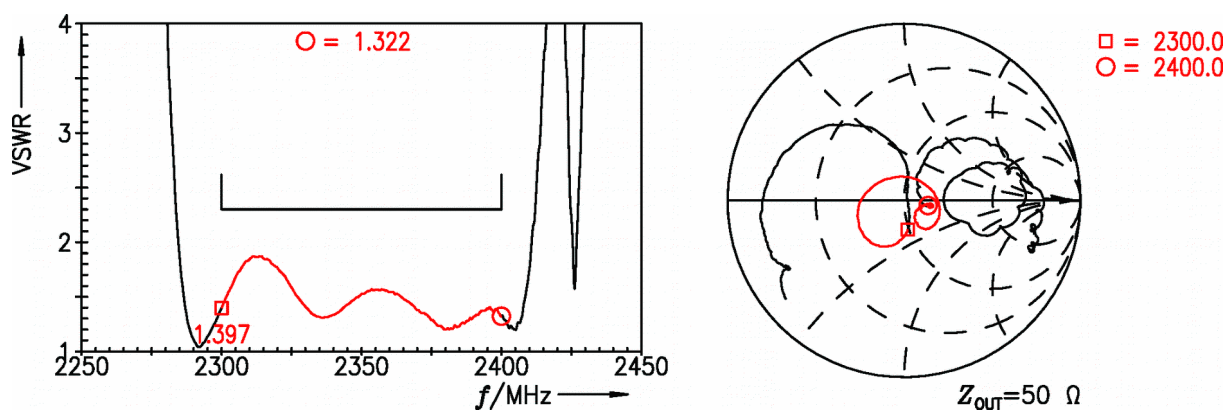


Figure 6: Reflection coefficient at OUT port.

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10 Packing material

10.1 Tape

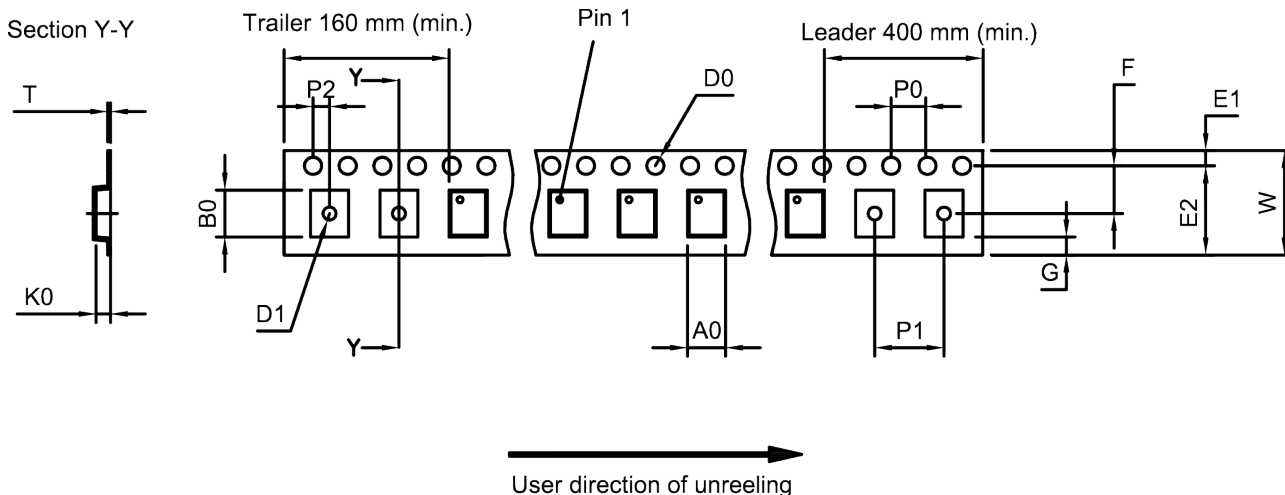


Figure 7: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	1.27±0.05 mm	E ₂	6.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	1.57±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.25±0.03 mm
D ₁	0.5±0.1 mm	K ₀	0.62±0.05 mm	W	8.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

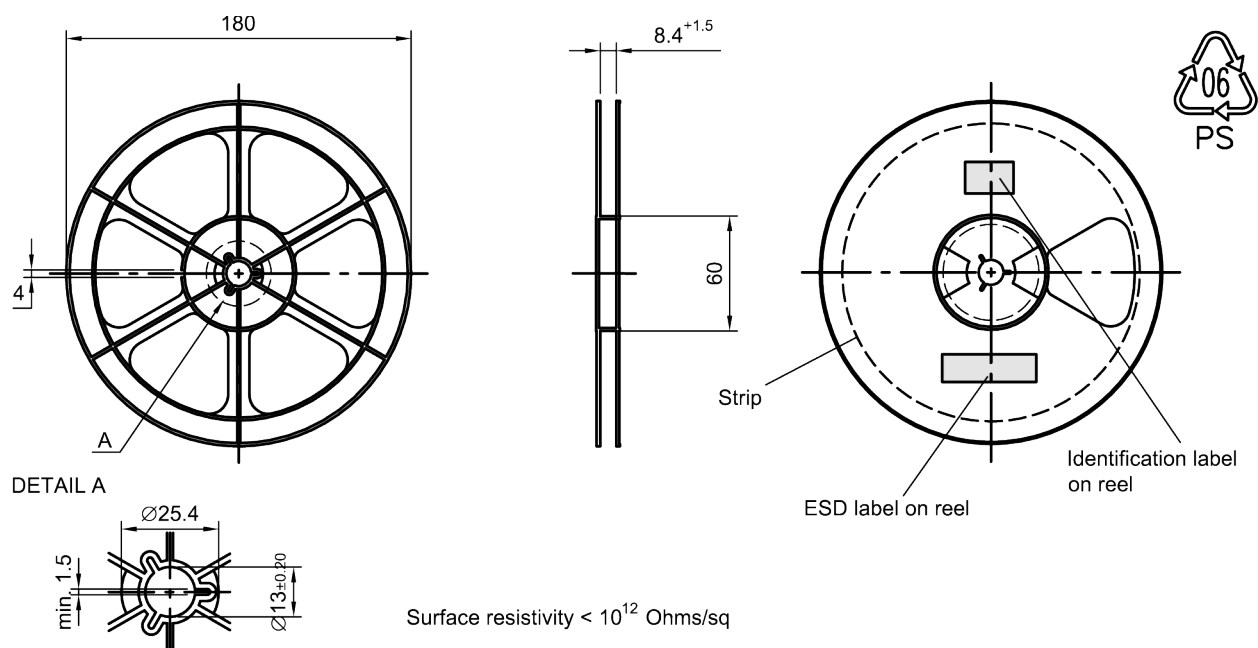


Figure 8: Drawing of reel (first-angle projection) with diameter of 180 mm.

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Dimensions [mm]

X = 220±5

Y = 235±5

Sealing area 10±3

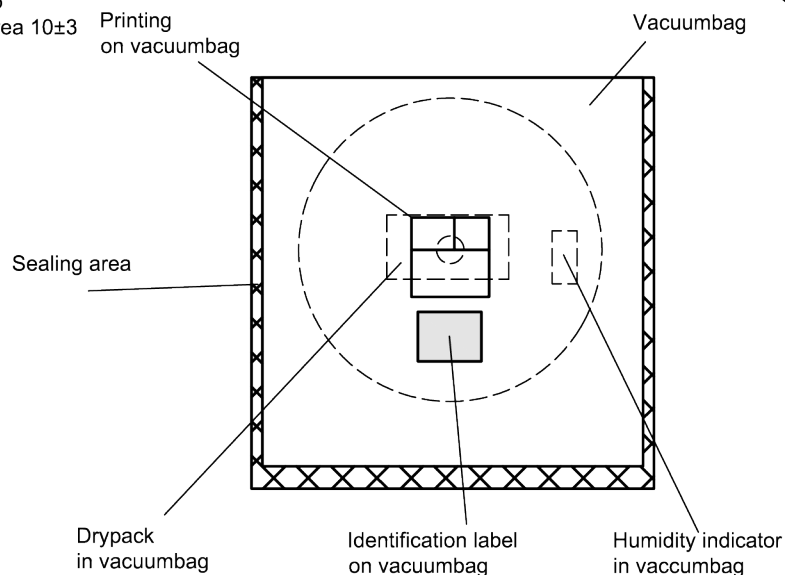


Figure 9: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

Dimensions [mm]

L = 188

B = 188

H = 30

Tolerance ±5

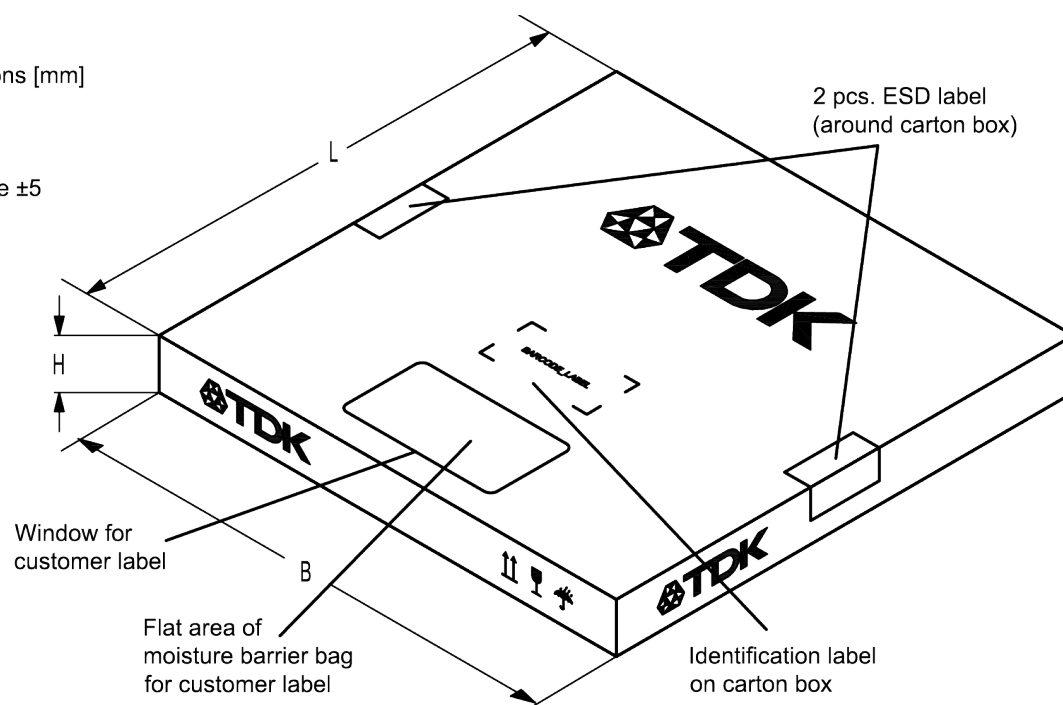


Figure 10: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

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The 4 digit type number of the ordering code,
is encoded by a special BASE32 code into a 3 digit marking.

e.g., B3xxxxB**1234**xxxx,

Example of decoding type number marking on device

in decimal code.

16J

=>

1234

$1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0$

=

1234

The BASE32 code for product type B4352 is 480.

■ Lot number:

The last 5 digits of the lot number,
are encoded based on a special BASE47 code into a 3 digit marking.

e.g., **12345**,

Example of decoding lot number marking on device

in decimal code.

5UY

=>

12345

$5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0$

=

12345

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

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12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	$\leq 3 \text{ K/s}$
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
$T > 220 \text{ °C}$	30 s to 70 s
$T > 230 \text{ °C}$	min. 10 s
$T > 245 \text{ °C}$	max. 20 s
$T \geq 255 \text{ °C}$	–
peak temperature T_{peak}	250 °C $\pm 5 \text{ °C}$
wetting temperature T_{min}	230 °C $\pm 5 \text{ °C}$ for 10 s $\pm 1 \text{ s}$
cooling rate	$\leq 3 \text{ K/s}$
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

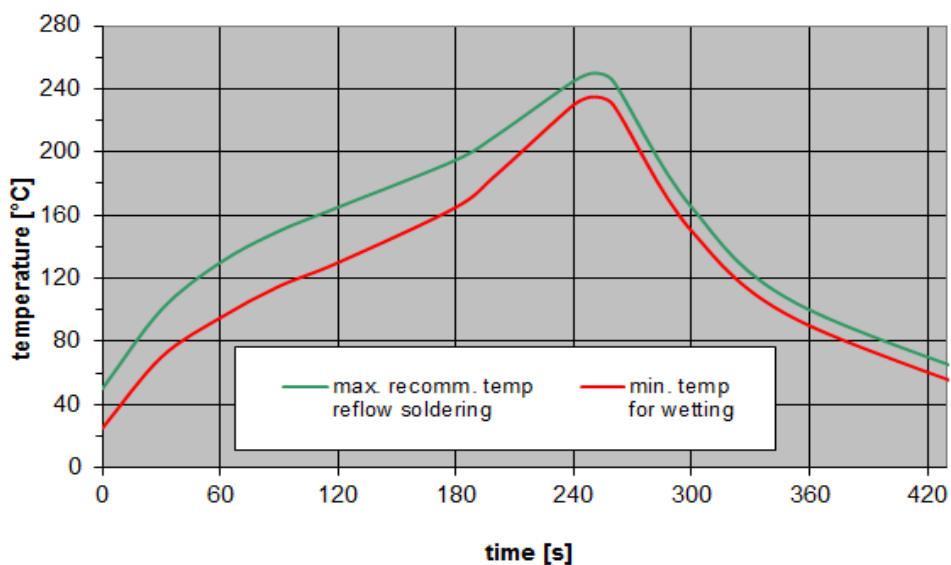


Figure 11: Recommended reflow profile for convection and infrared soldering – lead-free solder.

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13 ESD protection of SAW filters

SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

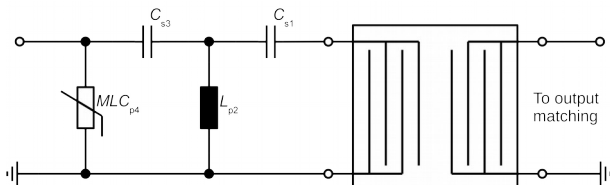


Figure 12: MLC varistor plus ESD matching.

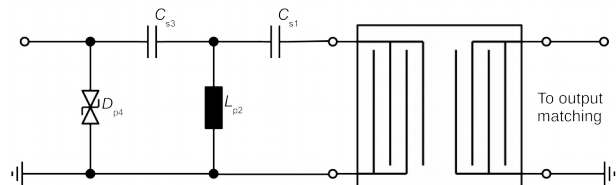


Figure 13: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

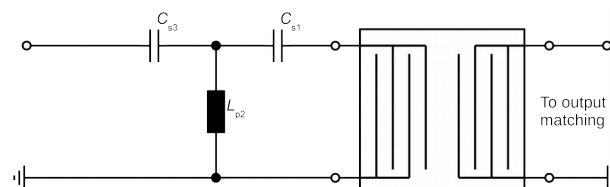


Figure 14: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to EPCOS Application report: “**ESD protection for SAW filters**”. This report can be found under www.epcos.com/rke. Click on “Applications Notes”.

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14 Annotations

14.1 Matching coils

See TDK inductor pdf-catalog <http://www.tdk.co.jp/tefe02/coil.htm#aname1> and Data Library for circuit simulation <http://www.tdk.co.jp/etvcl/index.htm>.

14.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

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15 Cautions and warnings

15.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

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